

Datasheet revision 1.1

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Thermally Stable Solder Paste WS (Water-Soluble) Sn96.5/Ag3.0/Cu0.5 T4 (35g syringe)

Product Highlights Revolutionary Formula: No Refrigeration Required! Printing speeds up to 100mm/sec Long stencil life Wide process window Excellent Wetting with Moderate Activity (REM0) Flux Water-Soluble Easily cleaned with water (60°C+)

Low voiding Compatible with most board finishes Dispense grade Compatible with enclosed print heads **RoHS 3 and REACH compliant**

Long Stonon nic		Dispense grade		
Wide process window		Compatible with e	nclosed print heads	
Excellent Wetting with Moderate Activity (REM0) Flux		RoHS 3 and REA	CH compliant	
Water-Soluble Easily clean				
Specifications			A Physical Section 1995	
Alloy:	Sn96.5/Ag3.0/Cu0.5		4599	0
Mesh Size:	Τ4			MI20 Ha
Micron (µm) Range:	20-38			a sta
Flux Type:	Synthetic Water-Soluble			
Flux Classification:	REM0 (Residue must be wat	er-washed at 60°C+ afte	er reflow)	
Metal Load:	86% Metal by Weight		,	
Melting Point:	217°C (423°F)			
Packaging:	35g/10cc Syringe			
Shelf Life:	Refrigerated >6 months, Unr	efrigerated >6 months	*See notes below:	
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<u>*Shelf Life Notes:</u> Chip Quik® solder paste is good past its quoted shelf life, regardless of refrigeration. Before use, visually inspect the solder paste to ensure it is not dried out or clumpy, or check stencil release. If stored in a jar, stir the product thoroughly for 2-3 minutes before inspection and use.

Chip Quik® solder paste is manufactured using high quality synthetic flux and precision atomized metal powder. Chip Quik® solder paste is guaranteed for 12 months from date of manufacture, regardless of refrigeration. If you have any issues with our solder paste, please contact Chip Quik® directly for no charge warranty replacement. Please retain original bill of sale, and solder paste in original container as we may request its return for internal R&D testing purposes.

Printer Operation

Print Speed: 25-100mm/sec Squeegee Pressure: 70-250g/cm of blade Under Stencil Wipe: Once every 10-25 prints, or as necessary

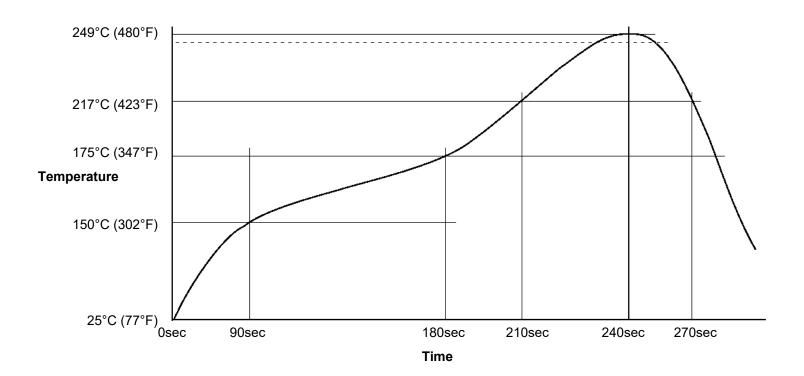
Stencil Life >8 hours @ 20-50% RH 22-28°C (72-82°F) >4 hours @ 50-70% RH 22-28°C (72-82°F)

Stencil Cleaning Automated stencil cleaning systems for both stencil and misprinted boards. Manual cleaning using isopropyl alcohol (IPA).

Storage and Handling Store at 3-25°C (37-77°F). Do not freeze. Refrigeration is not required, but will extend shelf life. Allow 4 hours for solder paste to reach an operating temperature of 20-25°C (68-77°F) before use.

Transportation

This product has no shipping restrictions. Shipping below 0°C (32°F) or above 25°C (77°F) for normal transit times by ground or air will not impact this product's stated shelf life.



Test Results

Test Requirement	Result
IPC-TM-650: 2.3.32	L: No breakthrough
IPC-TM-650: 2.6.15	L: No corrosion
IPC-TM-650: 2.3.28.1	L: <0.05%
IPC-TM-650: 2.6.14.1	L: <1 decade drop
IPC-TM-650: 2.6.3.7	L: ≥100MΩ
IPC-TM-650: 2.4.44	37g
IPC-TM-650: 2.4.34.4	Print: 155-215, Dispense: 80-115
IPC-TM-650: 3.4.2.5	Clear and free from precipitation
Electronic Industry Citizenship Coalition (EICC)	Compliant
Articles 33 and 67 of Regulation (EC) No 1907/2006	Contains no substance >0.1% w/w that is listed as a SVHC or restricted for use in solder materials
	IPC-TM-650: 2.3.32 IPC-TM-650: 2.6.15 IPC-TM-650: 2.3.28.1 IPC-TM-650: 2.6.14.1 IPC-TM-650: 2.6.3.7 IPC-TM-650: 2.4.44 IPC-TM-650: 2.4.34.4 IPC-TM-650: 3.4.2.5 Electronic Industry Citizenship Coalition (EICC) Articles 33 and 67 of Regulation (EC)

Conforms to the following Industry Standards:	
J-STD-004B, Amendment 1 (Solder Fluxes):	Yes
J-STD-005A (Solder Pastes):	Yes
J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders):	
RoHS 3 Directive (EU) 2015/863:	Yes